

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
17 November 2005 (17.11.2005)

PCT

(10) International Publication Number
WO 2005/108487 A1

(51) International Patent Classification⁷: **C08L 63/00**

PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(21) International Application Number:
PCT/US2005/012264

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(22) International Filing Date: 12 April 2005 (12.04.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/564,782 22 April 2004 (22.04.2004) US

(71) Applicant (for all designated States except US): **HENKEL CORPORATION** [US/US]; 1001 Trout Brook Crossing, Rocky Hill, Connecticut 06067 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **CHAN, Bruce, C. B.**, [US/US]; 14651 Clearbrook Drive, Chino Hills, California 91709 (US). **TODD, Michael, George**, [US/US]; 6999 Rutgers Drive, Anaheim Hills, California 92807 (US). **EDWARDS, Maurice, Earl**, [US/US]; 3431 Casco Court, Hacienda Heights, California 91745 (US).

(74) Agents: **CUNNINGHAM, Marina, E.**, et al.; McCormick, Paulding & Huber LLP, 185 Asylum Street, CityPlace II, Hartford, Connecticut 06103-3402 (US).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Declarations under Rule 4.17:

- as to the identity of the inventor (Rule 4.17(i)) for the following designations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)
- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations

Published:

- with international search report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHODS FOR IMPROVING THE FLUX COMPATIBILITY OF UNDERFILL FORMULATIONS

(57) Abstract: In accordance with the present invention, it has been discovered that the addition of one or more cationic catalyst(s), such as onium salts as defined herein, provides improved flux compatibility of underfill formulations in the presence of flux, flux residues and/or reaction products thereof. Accordingly, there are provided methods for improving the flux compatibility of underfill formulations in the presence of flux, flux residues and/or reaction products thereof. In accordance with another embodiment of the present invention, there are provided methods for improving HAST performance of underfill formulations, especially in the presence of flux, flux residues and/or reaction products thereof. In accordance with another embodiment of the present invention, there are provided methods for preparing underfill formulations having improved flux compatibility, especially in the presence of flux, flux residues and/or reaction products thereof. In yet another embodiment of the present invention, there are provided methods for adhesively attaching and/or encapsulating electronic components, especially in the presence of flux, flux residues and/or reaction products thereof. In a further embodiment of the present invention, there are provided articles produced by the above-described processes.

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